Design of an Integrated Modular Motor Drive

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Abstract

**In this study, design of an Integrated Modular Motor Drive (IMMD) is performed. The design is based on a modular fractional slot concentrated winding permanent magnet synchronous machine (FSCW-PMSM) and power stage with gallium nitride (GaN) power field effect transistors (FETs). Suitable slot/pole combination and winding configuration are obtained to maximize the stator winding factor as well as reduce the space harmonics on the modular motor. Optimum selection of number of series and parallel motor drive modules is achieved and power device selection is performed based on loss characterization. The performance of the system is obtained with Ansys/Maxwell for the motor and with MATLAB/Simulink for the power stage. The efficiency of the motor drive is enhanced by 2% compared to a conventional motor drive power stage. Power density values larger than 15 W/cm3 has been achieved which is not attainable with conventional motor drive systems.**

# 1. Introduction

In conventional motor drive systems, the drive units are placed in separate cabinets which increases the overall weight and volume of the system and decreases the power density of the system. Furthermore, the drive units are connected to the motor by means of long cables which causes transient voltage overshoots due to the high frequency pulse width modulation (PWM) operation.

A novel concept called Integrated Modular Motor Drives (IMMDs) has been proposed in the last few years suggesting that all the components of the motor drive system can be integrated onto the motor including power electronics, control electronics, passive components and heat sink (ref). By doing so, the power density of the system can be enhanced significantly which is very critical in aerospace and electric traction applications (ref). In addition to that, cost reduction up to 20% is possible thanks to the elimination of enclosures and connection equipment (ref). Moreover, the absence of connection cables yields less leakage current on the winding insulation which will extend the lifespan of the motor as well as minimize electromagnetic interference (EMI) problems (ref).

In addition, the overall system is segmented with modules sharing the total power equally. By this way, the fault tolerance of the system is increased (ref). The current and voltage ratings of the power semiconductor devices can also be decreased by modularization. Moreover, the components which produce heat due to power loss are spread and distributed in a wider surface area which makes the thermal design more convenient as well as decreases the possible of hot spot formation (ref). Finally, the manufacturing, installation and maintenance costs are considered to decrease thanks to the modular structure (ref).

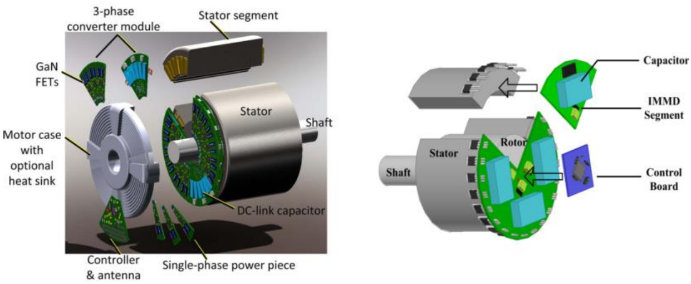
Integration of the motor and drive also brings several challenges. Firstly, fitting all the drive components to the available space requires size optimization and careful layout design (ref). Second, it is difficult to cool the motor and drive simultaneously since they both produce heat (ref). Furthermore, all the electronic components are subjected to a higher ambient temperature and continuous vibration and should be selected accordingly (ref).

To overcome these challenges, it has been proposed in the literature that wide band gap (WBG) power semiconductor devices such as Gallium Nitride (GaN) can be used which are capable of operating at high frequencies (ref). By doing so, the size of the passive components can be reduced as well as the size of the heat sink thanks to superior efficiency values (ref). On the other hand, high frequency operation highlights the parasitic components on the power stage and gate drive circuits which makes layout design critical (ref).

In this paper, design of an IMMD system is presented with enhanced power density, increased efficiency and enhanced fault tolerance capability. In Section 2, basic structure and current technology prospects of IMMDs are introduced. In section 3, design of the system including the motor and the drive is explained. In section 4, simulation results are presented and in section 5, conclusions are given.

**2. Basic Structure of IMMD**

There are several types of integration of the motor drive onto the motor. In this paper, integration into the stator back iron is considered, which also allows the modularization of the system. In this configuration, one module is composed of a stator pole piece, a concentrated coil and a power converter dedicated to its own winding along with its controller. Examples of such a structure can be seen in Fig. 1 (ref).



**Fig. 1.** IMMDs with stator back-iron integration (ref)

Each stator winding belonging to different pole pairs on the stator are usually connected in series to form one phase of the stator in conventional motors. On the other hand, the windings in different poles can be connected to separate motor drive units in modular motors. These types of motors are also called split-winding motors (ref) and the redundancy and fault tolerance of the system is enhanced thanks to this modularization. Moreover, the motor drive modules can be connected with different configurations which makes the design more flexible.

A general block diagram of one module of an IMMD system is shown in Fig. 2 (ref). On the machine pole, concentrated windings are preferred for their easy manufacturing and suitability for split-winding stators, especially in modular motors. Fractional slot concentrated winding (FSCW) permanent magnet synchronous motors (PMSMs) are very common in IMMD studies thanks to their high power density, high torque density, low cogging torque and good fault tolerance capability (ref).

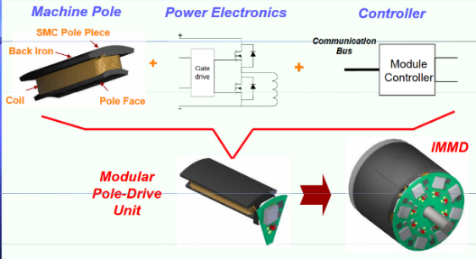


Fig. 2. General block diagram of one module of an IMMD (ref)

As for the power electronics, many different topologies have been proposed for AC motor drive systems such as, two-level inverter, multilevel neutral point clamped inverter, multilayer flying capacitor inverter, inverter with high frequency transformer etc. (ref). As mentioned previously, for a modular motor drive, several other motor drive topologies become available thanks to the design flexibility. Furthermore, the aforementioned topologies can be connected in series and/or parallel on the DC link to form a new topology. Series and parallel connection of motor drive inverter modules on the DC link are shown in Fig. 3 alongside with a conventional motor drive (ref). These types of connections are possible due to the fact that the windings, which are split and hence electrically isolated, do not cause circulating currents among the inverter modules. The major advantage of this possibility is to be able to split the voltage and/or current requirement of each inverter. One practical usage of this fact is the availability of low voltage power semiconductor device utilization such as GaN in case of high DC link voltage.



Series Parallel Conventional

Fig. 3. Different motor drive inverter connections for a modular motor (ref)

The employability of GaN devices is especially crucial for IMMD systems because these devices are one of the so-called WBG type semiconductor devices. These devices have much higher switching speeds compared to conventional silicon based devices such as Insulated Gate Bipolar Transistors (IGBTs) and admissible on-state losses which make them very efficient [ref]. Moreover, they have higher maximum junction temperatures [ref]. The volume reduction challenge of IMMDs can be addressed by the utilization of GaNs thanks to higher efficiency which makes cooling easier, and their fast switching speed which enables high switching frequencies reducing the size of passive components. In high power applications, the maximum switching frequency which can be applied to an IGBT is limited to 20 kHz, whereas GaNs can be used with frequencies as high as 100 kHz in applications with kW range [ref]. Another reason is that the efficiency of the system is high not only in rated power, but also for a wide range of output power [ref]. As a matter of fact, GaNs have been utilized in most of the very first IMMD prototypes thanks to these reasons [ref].

**3. Design of the IMMD System**

The design process of the IMMD system can be considered in twofold: design of the motor and design of the drive. However, they should be considered simultaneously for an integrated system as one side affects the other significantly. The first assumption in the design process is that the motor drive input is a passive diode bridge rectifier with an LC DC link filter. The effects of this rectifier module on the rest of the system are kept out of the scope of this study such that the input to the motor drive DC link is a pure DC current. The machine is a three-phase permanent magnet synchronous machine having a modular stator with fractional slot concentrated windings. Considering the applications where IMMD concept is suitable, it will be a low speed high torque motor design. The system parameters used in the design process are shown in Table 1.

The first parameters to be decided for the design is the total number of three-phase modules. As stated before, the number of series or parallel connected modules can be varied according to the voltage and current requirements and the system parameters such as the DC link voltage and total output power. It has also been specified that GaN transistors should be used to reach the efficiency ratings and meet the volume reduction challenge. Blocking voltage rating of the current GaN transistors which are commercially available is 650V at most [ref]. If two-level full-bridge motor drive inverter modules are used, the minimum power semiconductor blocking voltage rating in this design is 810V. This value is calculated based on a safety margin considering the voltage overshoot effects due to parasitic inductances and high switching speed. It is clear that, at least two series modules should be used with the aforementioned GaN devices. This also makes the total number of modules an even number.

Table 1. The system parameters used in IMMD design process

|  |  |
| --- | --- |
| DC link voltage, Vdc | 540 V |
| Total output power, Pout | 8 kW |
| Motor efficiency aim, ηm,a | 96% |
| Drive efficiency aim, ηd,a | 98% |
| Rated speed, Nr | 600 rpm |

There are various parameters which effect the number of parallel modules. One of them is the required power rating of each module which effect the current ratings of the semiconductor devices and drive efficiency. Another one is the number of stator slots. Instead of number of slots per pole per phase (q) used in conventional systems, a new parameter, number of slots per module per phase (w) should be defined in IMMDs. For example, if two series and two parallel modules are used, the minimum number of slots that can be used is 24. Lastly, the effect of interleaving and its utilization for minimization of DC link capacitor bank size is considered to determine the number of modules. In [ref-u], the effect of the number of modules and applied interleaving angle to the current ripple on the DC link capacitor bank is studied for an IMMD system, and it has been shown that selecting four modules yields best results in terms of DC link capacitor size. Using that result, it is decided that a total number of 4 modules which are 2-series and 2-paralel should be used. The schematic diagram of the suggested IMMD system topology is shown in Fig. 4.



Fig. 4. Schematic diagram of the suggested IMMD topology

**3.1. Design of the motor**

Motor tasarımı

Every table

The resultant motor parameters are shown in Table 2.

Table 2. The resultant motor parameters

|  |  |
| --- | --- |
| Number of stator slots, Qs | 24 |
| Number of rotor poles, p | 20 |
| Stator winding factor, kws | 0.933 |
| Motor axial length, L | 150 mm |
| Stator outer diameter, Dos | 230 mm |
| Stator inner diameter, Dis | 150 mm |
| Air gap length, lg | 1 mm |
| Magnet thickness, lm | 5 mm |
| Number of turns per coil side, zQ | 30 |
| Stator fill factor, kcu | 0.6 |

**3.2. Design of the drive**

The selection of power semiconductor device is based on voltage and current requirements. Among the suitable alternatives, the most efficient device should be chosen. There are two GaN transistor types in the market which have breakdown voltage ratings as high as 650V, cascade GaNs manufactured by Transphorm and enhancement mode (e-mode) GaNs manufactured by GaN systems [ref].

GaN seçiminde ilk olarak gerekli anma akımı değeri hesaplanmalıdır. Bunun için de, stator sargıları üzerinde indüklenen gerilimden yola çıkılabilir. Akım hesabı

Bir modülün bir fazına ait stator sargı indüklenen gerilimi etkin değeri Eşitlik 1’de gösterilmiştir. Bu eşitlikte, Nphm, faz başına ve modül başına sarım sayısı olarak tanımlanabilir. Bu çalışmada sarım içi tur sayısı 22 olarak seçilmiştir. Toplam tur sayısı ise Eşitlik 2’de gösterildiği gibi 88 olarak bulunmuştur. Ayrıca motor hava aralığındaki tepe akı yoğunluğu, motor nüvesini doyuma ulaştırmayacak şekilde 0.9 olarak alındığında, kutup başına akı yoğunluğu Eşitlik 3’te gösterildiği gibi bulunabilir. Kesirli oluklu makinalara yönelik var olan tablolara bakıldığında sarım faktörü 48/40 oluk/kutup oranı için 0.933’tür [9]. Son olarak, gerekli anma rotor hızı için gerekli olan stator akım frekansı da Eşitlik 4’teki gibi bulunmuş ve faz ve modül başına indüklenen gerilim etkin değeri 69.6 V olarak hesaplanmıştır. Motor sürücü modüllerinin sinüzoidal darbe genişlik modülasyonu ile anahtarlandığında (S-PWM) gerekli olan modülasyon endeksi değeri Eşitlik 5’teki gibi 0,8 olarak hesaplanabilir. Bu hesapta modül ve faz başına sürücü çıkış gerilimi (Vp-rms), yüzde 10’luk gerilim düşümü hesaba katılarak 76.5 V olarak alınmış ve modül başına DA gerilim (Vdc-m), seri bağlı modül sayısından elde edilmiştir. Sonuç olarak, motor güç faktörü ve anma verimi kullanılarak faz ve modül başına sürücü çıkış akımı Eşitlik 6’da gösterildiği gibi 10,75 amper olarak bulunmuştur.

|  |  |
| --- | --- |
|  | (1) |
|  | (2) |
|  | (3) |
|  | (4) |
|  | (5) |
|  | (6) |

One device from each type is selected having similar ratings as well as an IGBT for comparison purposes, which are shown in Table X [ref].

Güç yarıiletken kayıpları, transistor iletim kayıpları (Ptc) ve anahtarlama kayıpları (Pts), ters paralel diyot (veya ters iletim transistor) iletim kayıpları (Pdc) ve anahtarlama kayıpları (Pdr) şeklinde incelenmiştir. Sözü geçen kayıpların hesaplanmasında kullanılan formüller Eşitlik 7-11’de görülebilir. Bu eşitliklerde, Eon ve Eoff açılma ve kapanma enerjileri, Icp ve Iep iletim ve ters iletim tepe akımları, Vce,sat doyma gerilim düşümü, Rds,on iletim durumu direnci, Vec diyotun gerilim düşümü, Irr ve trr diyotlar için toparlanma akımı ve zamanı, ve Vce,p ise ters toparlanma gerilimi tepe değeridir. Kayıp analizi sonuçları ve karşılaştırmalar 4. Bölümde sunulmuştur.

|  |  |
| --- | --- |
|  | (7) |
|  | (8) |
|  | (9) |
|  | (10) |
|  | (11) |

Table X. Alternative devices for transistor selection [ref]

|  |  |  |  |
| --- | --- | --- | --- |
| Transistör | FP35R12KT4P | TPH3205WSB | GS66508B |
| Tipi | IGBT | Cascode GaN | E-mode GaN |
| Üretici | Infineon | Transphorm | GaN systems |
| Gerilim | 1200 V | 650 V | 650 V |
| Akım | 35 A | 35 A | 30 A |
| Vce,sat | 2,15 V | - | - |
| Rds,on | - | 60 mΩ | 50 mΩ |

**4. Simulation Results**

Equations

**4.1. 2D FEM simulations of the motor**

Captions example, write "Time (s) ". Do not label axes only with units.

**4.2. Power stage simulations**

Konvansiyonel IGBT’li motor sürücü ile iki farklı tipte GaN’lı TMMS sistemi kayıp analizi karşılaştırmalı sonuçları Şekil 6‘da gösterilmiştir.



Şekil 6. Konvansiyonel motor sürücü sistemi ile TMMS sistemi kayıp analizi sonuçları

Kayıp analizi sonuçlarına bakıldığında GaN kullanımı ile her iki tipte de anahtarlama frekansı beş katına çıkartılmasına rağmen yarıiletken kayıplarının toplamda hemen hemen yarıya düştüğü gözlenmiştir. IGBT’lerde pratikte anahtarlama frekansı üst sınırı 20 kHz’tir, bu nedenle daha yüksek frekanslarda analiz yapılmamıştır. Kayıp bileşenleri ayrı ayrı incelendiğinde ise, öngörüldüğü gibi kayıptaki ana düşüş transistor ve diyot anahtarlama kayıplarında olmaktadır. Diğer bir taraftan, diyot iletim kayıplarında büyük bir değişim gözlenmemiştir ancak transistor iletim kayıpları GaN’larda daha yüksek olmuştur. Bu durumun başlıca nedenleri, IGBT’lerin yüksek akımlı uygulamalarda iletim durumunda genel olarak iyi performans göstermesi ve GaN gibi WBG anahtarların henüz teknolojik olarak istenilen iletim durumu düzeyine ulaşamamasıdır. Diğer bir neden ise sistemin iki paralel ve iki seri modülden oluşmasıdır. Tamamının paralel bağlanmasına durumuna oranla her bir modül iki kat fazla akım taşımakta ve GaN’larda iletim kayıpları akımın karesi ile artmaktadır. Sonuç olarak, 100 kHz anahtarlama frekansında hem Kaskod hem de E-mode GaN’da yaklaşık %98 verime ulaşılmıştır ve daha yüksek verim hedeflendiğinde anahtarlama frekansı düşürülebilir.



Şekil 7. DA bara gerilimi dalgalanması



Şekil 7. DA bara gerilimi dalgalanması



Şekil 7. DA bara gerilimi dalgalanması

**5. Conclusions**

Define abbreviations and

**6. References**

[1] J. K. Author, "Name of paper", *Abbrev. Title of Periodical*, vol. *x,* no. *x,* pp*. x-x,* Abbrev. Month, year.

[2] J. K. Author, "Title of book", Abbrev. of Publisher, City of Publisher, Country, year*.*

[3] J. K. Author, "Title of paper", in *Unabbreviated Name of Conf.*, City of Conf., Abbrev. State (if given), year, pp. *x-x.*

[4] J. K. Author, "Title of thesis", M.S. thesis, Abbrev. Dept., Abbrev. Univ., City of Univ., Abbrev. State, year.

[5] *Title of Standard*, Standard number, date.

[6] J. K. Author. (year, month day). *Title* (edition) [Type of medium]. Available: http://www.(URL)